Wire Wound Chip Common Mode Chokes

ACT3225 Series

FEATURES

- Winding type realizes small size and low profile
- Prevention of common mode noise at high frequency
- Excellent solderability
- Operating temperature -40~+125 ℃ (Including self temperature rise)

APPLICATIONS

Common mode noise filtering for automotive CAN-BUS and signal line

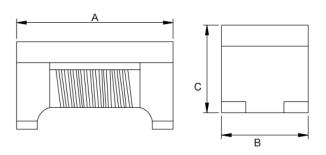
Explanation of Part Number

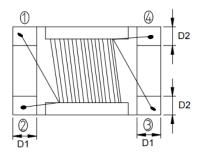
ACT 3225L- 101-2P- T F

1 2 3 4 5 6

- ♦ 1:Product Series:Wire Wound Chip Common Mode Filters
- ♦ 2:Dimensions:
- ♦ 3:Inductance(µH):101=100uH
- ◆ 4:Number of Lines:2P=2 lines
- ◆ 5:Packing(Tape & Reel)
- ♦ 6:F:Hazardous Substance Free Products

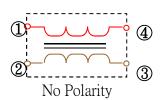
Shapes and Dimensions [mm]



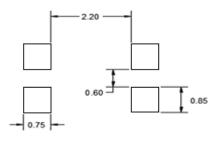


A: $3.3 \pm 0.2 \text{ mm}$ B: $2.5 \pm 0.2 \text{ mm}$ C: 2.50 mmMaxD1:0.55 ± 0.15mm D2:0.75 ± 0.2mm

Equivalent circuit



Land Pattern: [mm]

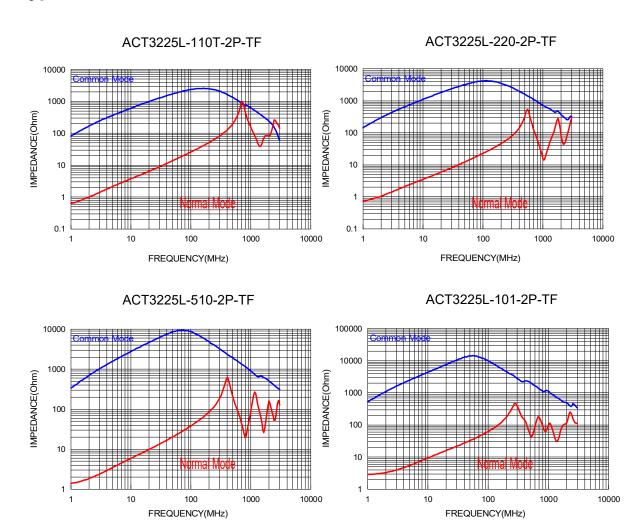




Electrical Characterisitics:

Part Number	Common mode Impedance (Ω) [10MHz]		Inductance(μ H) +50/-30% [100kHz/0.1V]	DC Resistance (Ω) max.	Rated Current (mA) max.		IR (M Ω) min.
ACT3225L-110-2P-TF	300min	550 typ.	11	0.4	300	80	10
ACT3225L-220-2P-TF	500min	1100typ.	22	0.5	250	80	10
ACT3225L-510-2P-TF	1000min	2600typ.	51	0.7	200	80	10
ACT3225L-101-2P-TF	2200min	5100typ.	100	1.5	150	80	10
ACT3225L-201-2P-TF	8000min	10000typ.	200	4.8	70	80	10

Typical Electrical Characteristics:

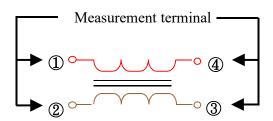




Test Equipment

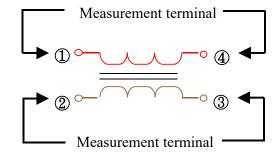
Inductance

Measured by using Agilent HP4284A Precision LCR Meter.



DC Resistance

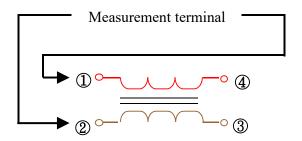
Measured by using Chroma 16502 mill ohm meter.



Insulation Resistance

Measured by using Chroma 19073

Measurement voltage: 50v, Measurement time: 60 sec.





Reliability Test

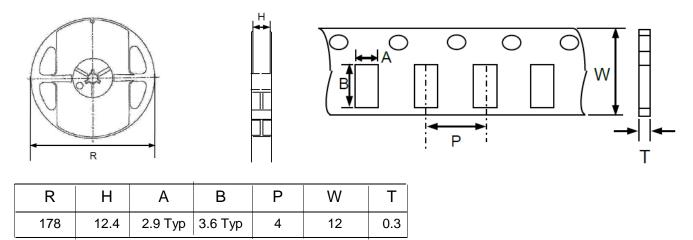
Operating temperature : -40 to +125℃		Storage temp and humidity : 20~25℃ ,60%RH max.		
Item	Specifications	Test conditions		
Board Flex	The forces applied on the right conditions must not damage the terminal electrode and the ferrite.	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 60 sec		
Terminal strength	The chip must not damage the terminal electrode and the ferrite.	Appendix 1 Note(AEC-Q200-006):Force of 1.8 kg for 60 seconds. Test Board		
Solderability	The electrodes shall be at least 95% covered with new solder coating.	Pre-heating: 150 °C, 1min Solder Composition: Sn/3.0Ag/0.5Cu Solder Temperature: 255±5 °C Immersion Time: 4±1sec		
Resistance to Soldering Heat	Appearance:No damage Inductance change shall be within ±20%.	Pre-heating: 150°C, 1min Solder Composition: Sn/Ag3.0/Cu0.5 Solder Temperature: 255±5°C Immersion Time: 10±1sec		
Resistance to Solvents	There must be no change in appearance or obliteration of marking.	Inductors must withstand 6 minutes of alcohol or water.		
Mechanical Shock	The forces applied on the right conditions must not damage the terminal electrode and the ferrite.	Pulse shape:Half-sine waveform Impact acceleration:100g Pulse duration: 6ms Number of shocks: 18 shocks (3 shocks for each face) Orientation:Bottom,top,left,right,front and rear faces		



Item	Specifications	Test conditions
Vibration	Appearance:No damage	Vibration waveform: Sine waveform
	Inductance change shall be	Vibration frequency: 10Hz~2000Hz
	within ±20%.	Vibration acceleration: 5g
		Sweep rate: 0.764386otcave/minute
		Duration of test: 12 cycles each of 3 orientations
		20 minutes for each cycle Vibration axes: X, Y & Z
High	Appearance:No damage	Temperature: 125±3°C
Temperature	(for microscope of MEIJI WF10X/22)	Time:1000hrs
Exposure	Inductance change shall be within ±30%.	Measured after exposure in the room condition for 24hrs
(Storage)		
Biased		Temperature: 85±2°C
Humidity		Relative Humidity: 85%
		Time: 1000hrs
		Measured after exposure in the room condition for 24hrs
Operational	-	Temperature : 125±2°C
Life		Appliend Current : Rated Current
		Time :1000±24 hrs
		Measured after exposure in the room condition for 24 hrs
Temperature		Total cycles: 1000 cycles
Cycling		Temperature Cycling Test Conditions : -40 to +125°C
		Soak Mode Condition: 30 minutes
		Measured after exposure in the room condition for 24hrs



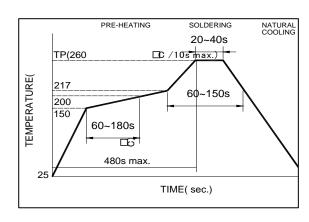
Packing Dimension



Packaging Quantity:1000PCS/Reel

Soldering Conditions

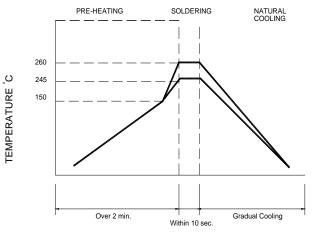
Figure 1. Re-flow Soldering (Lead Free)



Note:

- Preheat circuit and products to 150°C
- 260°C tip temperature (max)
- Reflow times: no more than 2 times
- Solder paste thickness: the best 0.08mm is ,but max is 0.1mm

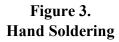
Figure 2.
Wave Soldering

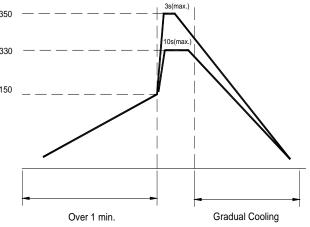


Note:

- Never contact the ceramic with the iron tip
- 1.0mm tip diameter (max)







Note:

Use a 20 watt soldering iron with tip diameter of 1.0mm.

Limit soldering time to 3 sec.